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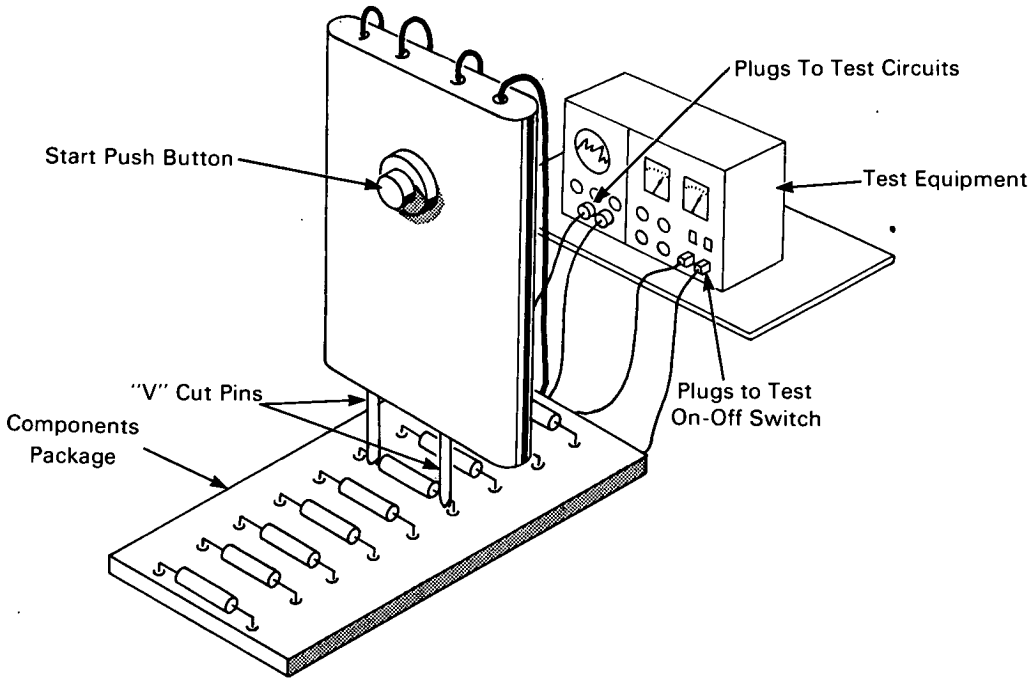
Brief 65-10243

NASA TECH BRIEF

Novel Probe Simplifies Electronic Component Testing



The problem: Testing of electronic components in volume has been a time consuming task involving unpackaging and repackaging for coded storage according to test results. Handling of small, sensitive components also results in a certain percent that must be discarded due to damage to leads, seals, etc.

The solution: A test probe that can be used in conjunction with standard equipment to test axial-lead components in their original packages.

How it's done: The test probe consists of a plastic case that holds two metal test pins, two leads to the test equipment circuits, two leads to the test equipment on-off switch, and a start button. The two metal test pins have v-shaped slots filed in their ends to receive the two axial leads of the component. The test probe is pushed against the two leads of the component (still in the original package) and the operator depresses the start button to begin the testing sequence. When the test sequence is completed, the operator moves the probe to the next component in the package and repeats the operation.

(continued overleaf)

Notes:

1. The test probe could readily be modified to test any type of electronic component with automatic or nonautomatic equipment.
2. With this device, a shipment of 17,000 diodes was tested, cataloged, and stored in six working days. Experience shows that at least three additional weeks would have been needed using the old method of unpackaging, testing, and repackaging.
3. Inquiries concerning this invention may be directed to:

   Technology Utilization Officer
   Goddard Space Flight Center
   Greenbelt, Maryland, 20771
   Reference: B65-10243

Patent status: NASA encourages the immediate commercial use of this invention. Inquiries about obtaining rights for its commercial use may be made to NASA, Code AGP, Washington, D.C., 20546.

Source: Warren F. Syner
(GSFC-342)